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**PATENT NUMBER and  
ISSUE DATE**

**U.S. UTILITY Patent Application**

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10081661	02/22/2002	438	597	2812	Nguyen Ha

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\*\*CONTINUING DATA VERIFIED:

**\*\* FOREIGN APPLICATIONS VERIFIED:**

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no	SAM-0313
Verified and Acknowledged Examiner's initials			
TITLE : Method of manufacturing interconnection line in semiconductor device			
U.S. DEPT. OF COMM./PAT. & TM-PTO-435(L(Rev. 12-94))			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.
<input type="checkbox"/> TERMINAL <b>DISCLAIMER</b>		PREPARED FOR ISSUE		Application Examiner
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